

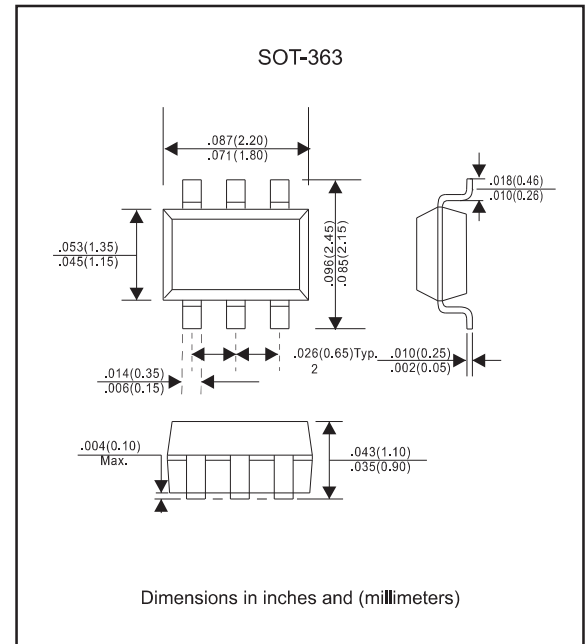
Features

- Surface mount package ideally suited for automatic insertion
- Fast switching
- Low leakage current
- Reverse voltage: 250V
- Low junction capacitance
- Average forward current: 200mA
- Compliant to Halogen-free

Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, SOT-363
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Mounting Position : Any

Package outline



Maximum ratings (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

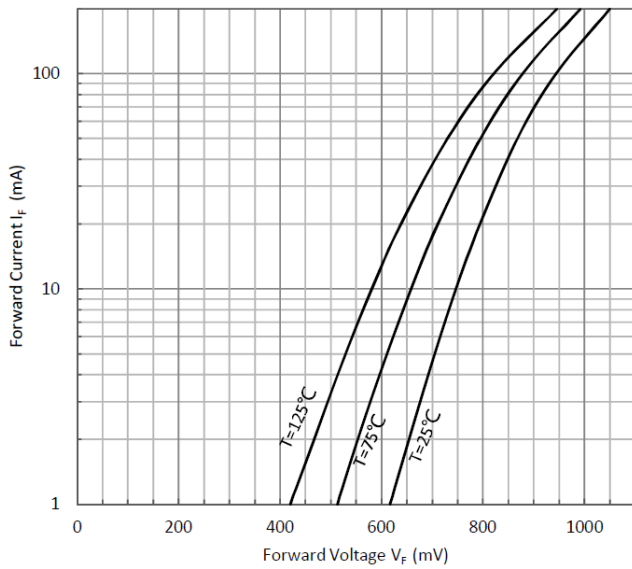
PARAMETER	SYMBOL	UNIT	Conditions	VALUE
Repetitive peak reverse voltage	V_{RRM}	V		250
Reverse voltage	V_R	V		250
Average forward current	I_{FAV}	mA		200
Non-repetitive peak forward surge current	I_{FSM}	A	8.3ms half-sine wave	1.7
Power dissipation	P_D	mW		200
Thermal Resistance Junction to Ambient Air	$R_{\theta JA}$	$^{\circ}\text{C/W}$		625
Maximum junction temperature	T_j	$^{\circ}\text{C}$		-55 ~+150
Storage temperature range	T_{stg}	$^{\circ}\text{C}$		-55 ~+150

Electrical characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

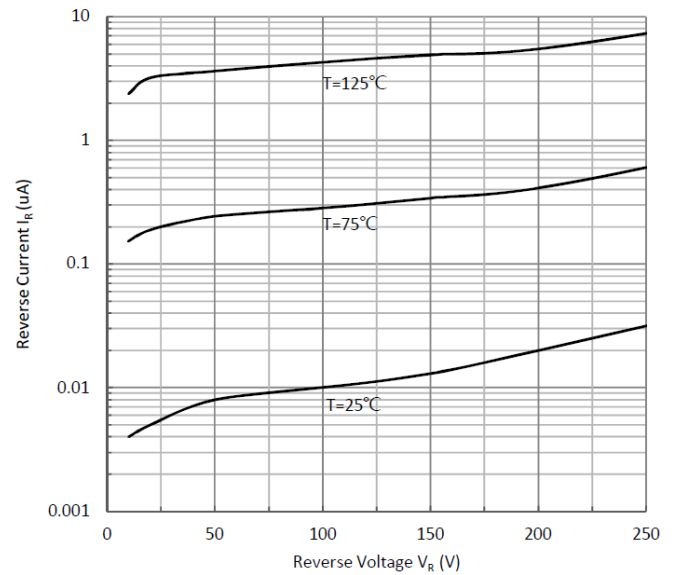
PARAMETER	Symbol	UNIT	Conditions	Min	Max
Breakdown Voltage	V_R	V	$I_R=100\mu\text{A}$	250	
Forward Voltage	V_F	V	$I_F=100\text{mA}$		1.05
			$I_F=200\text{mA}$		1.25
Reverse Leakage Current	I_R	nA	$V_R=200\text{V}$		100
Capacitance	C_j	pF	$V_R=0\text{V}, f=1\text{MHz}$		5
Reverse Recovery Time	T_{RR}	ns	$I_F=I_R=30\text{mA}, I_{rr}=1\text{mA}$		50

Rating and characteristics curves

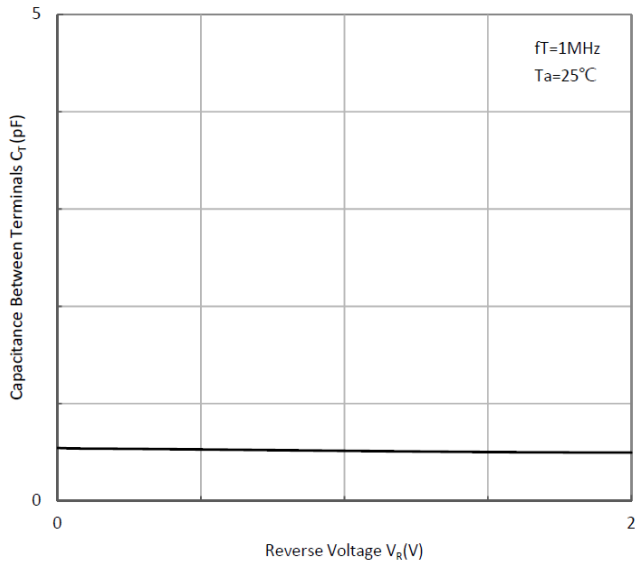
Forward Characteristics



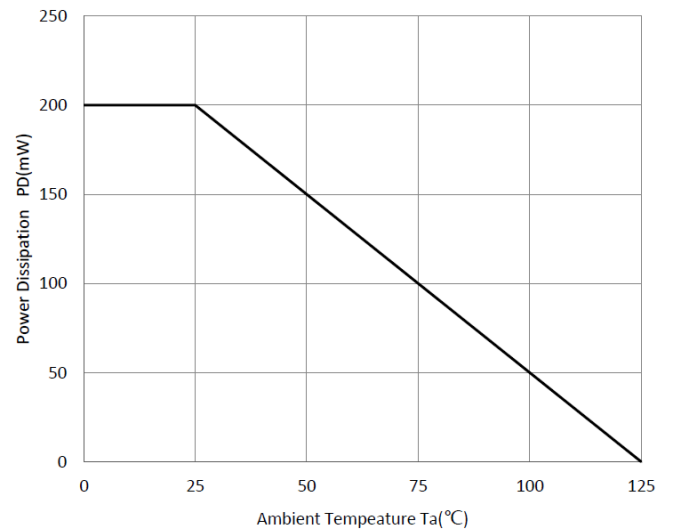
Reverse Characteristics



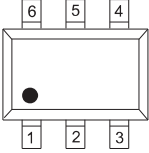
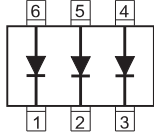
Capacitance Characteristics



Power Derating Curve

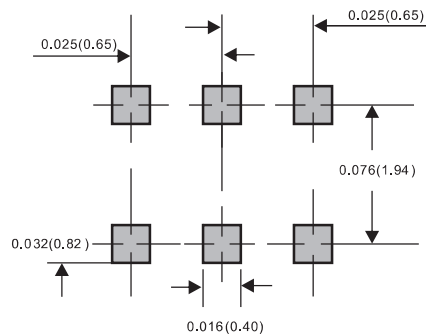


Pinning information

Type number	Marking code	Simplified outline	Symbol
BAS21TW	XJK		

Suggested solder pad layout

SOT-363



Dimensions in inches and (millimeters)